

PMP8671 REV B2 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C9	2	100pF	std	std	Capacitor, Ceramic, 50V, [temp], [tol], Capacitor, Ceramic, vvV, [temp], [tol]	0603
C2	1	0.22uF	std	std	Capacitor, Ceramic, 16V, [temp], [tol]	0603
C3	1	470pF	std	std	Capacitor, Ceramic, 50V, X7R	0603
C4	1	47nF	std	std	Capacitor, Ceramic, 50V, [temp], [tol]	0603
C5, C7	2	1uF	std	std	Capacitor, Ceramic, 16V, X7R, 20%	0603
C6	1	1nF	std	std	Capacitor, Ceramic, 50V, [temp], [tol]	0603
C8, C10, C11, C12, C15, C28, C100, C110, C120, C800	10	22uF	Std	Std	Capacitor, Ceramic, 25V, X7R, 15%	1210
D1	1	MBRS540	MBRS540	ONsemi	Diode, 5A, 40V	SMC
D99, D100	2	ZHCS1006	ZHCS1006	Zetex	Diode, Schottky, 900-mA, 60-V	SOT-23
J1, J2	2	D120/2DS	D120/2DS	OST	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch
L2	1	10uH	DRQ127-100-R	Cooper	Inductor, SMT, 6Arms, 34.4milliohm	0.492 x 0.492 inch
Q1	1	BSZ165N04NSG	BSZ165N04NSG	Infineon	MOSFET, Nch, Fast Switching, 40V, 31A, 16.5 milliohm	PP-1212
R1	1	422k	std	std	Resistor, Chip, 1/16W, 1%	0603
R2	1	10k	std	std	Resistor, Chip, 1/16W, 1%	0603
R3	1	2.0k	std	std	Resistor, Chip, 1/16W, 1%	0603
R4	1	2.7	STD	STD	Resistor, Chip 1/4 watt, ± 5%	1206
R5	1	15.8k	std	std	Resistor, Chip, 1/16W, 1%	0603
R7	1	10	std	std	Resistor, Chip, 1/16W, 1%	0603
R9	1	49.9	std	std	Resistor, Chip, 1/16W, 1%	0603
R10	1	1k	std	std	Resistor, Chip, 1/16W, 1%	0603
R11	1	0.03	Std	Std	Resistor, Chip, 1/2W, 1%	1812
TP1, TP8, TP11	3	5011	5011	Keystone	Test Point, Black, Thru Hole	0.125 x 0.125 inch
TP2, TP10	2	5010	5010	Keystone	Test Point, Red, Thru Hole	0.125 x 0.125 inch
TP4, TP5	2	5002	5002	Keystone	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch
TP7	1	5000	5000	Keystone	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch
U1	1	TPS40210DGS	TPS40210DGS	TI	IC, Low Cost Non-Synchronous Boost Controller	DGS10

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